



OPA404

Quad High-Speed Precision Difet® OPERATIONAL AMPLIFIER

FEATURES

- WIDE BANDWIDTH: 6.4MHz
- HIGH SLEW RATE: 35V/µs
- LOW OFFSET: ±750µV max
- LOW BIAS CURRENT: ±4pA max
- LOW SETTLING: 1.5µs to 0.01%
- STANDARD QUAD PINOUT

DESCRIPTION

The OPA404 is a high performance monolithic *Difet*[®](dielectrically-isolated FET) quad operational amplifier. It offers an unusual combination of very-low bias current together with wide bandwidth and fast slew rate.

Noise, bias current, voltage offset, drift, and speed are superior to BIFET[®] amplifiers.

Laser-trimming of thin-film resistors gives very low offset and drift—the best available in a quad FET op amp.

The OPA404's input cascode design allows high precision input specifications and uncompromised highspeed performance.

Standard quad op amp pin configuration allows upgrading of existing designs to higher performance levels. The OPA404 is unity-gain stable.

APPLICATIONS

- PRECISION INSTRUMENTATION
- OPTOELECTRONICS
- SONAR, ULTRASOUND
- PROFESSIONAL AUDIO EQUIPMENT
- MEDICAL EQUIPMENT
- DETECTOR ARRAYS



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SPECIFICATIONS

ELECTRICAL

At V_{CC} = $\pm 15 VDC$ and T_A = +25°C unless otherwise noted.

		OPA4	04AG, KP,	KU ⁽¹⁾	(OPA404B	G		OPA404SO	G	
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	ТҮР	MAX	MIN	ТҮР	MAX	UNITS
INPUT											
NOISE											
Voltage: f _O = 10Hz			32			*			*		nV/√Hz
f _O = 100Hz			19			*			*		nV/√ <u>Hz</u>
$f_0 = 1 kHz$			15			*			*		nV/√Hz
$f_0 = 10 \text{kHz}$			12			*			*		nV/√Hz
$f_B = 10Hz$ to $10kHz$			1.4			*			^		μVrms
$f_B = 0.1Hz$ to 10Hz			0.95 12			*			*		μVp-p
Current: $f_B = 0.1Hz$ to 10Hz $f_O = 0.1Hz$ thru 20kHz			0.6			*			*		fA, p-p fA/√Hz
°											
OFFSET VOLTAGE Input Offset Voltage	V _{CM} = 0VDC		±260	±1mV		*	±750		*	*	μV
KP, KU	*CM = 0*80		±200 ±750	±2.5mV			100				μν μV
Average Drift	$T_A = T_{MIN}$ to T_{MAX}		±3			*			*		μV/°C
KP, KU			±5								μV/°C
Supply Rejection	$\pm V_{CC}$ = 12V to 18V	80	100		86	*		*	*		dB
KP, KU		76	100								dB
Channel Separation	100Hz, $R_L = 2k\Omega$		125			*			*		dB
BIAS CURRENT											
Input Bias Current	$V_{CM} = 0VDC$		±1	±8		*	±4		*	*	pА
KP, KU			±1	±12							pА
OFFSET CURRENT											
Input Offset Current	$V_{CM} = 0VDC$		0.5	8		*	4		*	*	pА
KP, KU			0.5	12							pА
IMPEDANCE											
Differential			10 ¹³ 1			*			*		Ω pF
Common-Mode			1014 3			*			*		Ω pF
VOTAGE RANGE											
Common-Mode Input Range		±10.5	+13, –11		*	*		*	*		V
Common-Mode Rejection	$V_{IN} = \pm 10 VDC$	88	100		92	*		*	*		dB
KP, KU		84	100								dB
OPEN-LOOP GAIN, DC											
Open-Loop Voltage Gain	$R_L \ge 2k\Omega$	88	100		92	*		*	*		dB
FREQUENCY RESPONSE											
Gain Bandwidth	Gain = 100	4	6.4		5	*		*	*		MHz
Full Power Response	20Vp-p, $R_L = 2k\Omega$		570			*			*		kHz
	$V_0 = \pm 10V, R_L = 2k\Omega$	24	35		28	*		*	*		V/μs
Settling Time: 0.1%	Gain = -1 , R _L = $2k\Omega$		0.6 1.5			*			*		μs
	C _L = 100 pF, 10V Step		1.5								μs
	D alko	+14 5	12.2 42	0	*	*		*	*		
Voltage Output	$R_L = 2k\Omega$ $V_\Omega = \pm 10VDC$	±11.5 + ±5	-13.2, –13. ±10	0	*	*		*	*		V mA
Current Output Output Resistance	$v_0 = \pm 10$ VDC 1MHz, Open Loop	<u></u> 3	±10 80			*			*		mA Ω
Load Capacitance Stability	Gain = $+1$		1000			*			*		pF
Short Circuit Current		±10	±27	±40	*	*	*	*	*	*	mA
POWER SUPPLY											
Rated Voltage			±15			*			*		VDC
Voltage Range,											
Derated Performance		±5		±18	*		*	*		*	VDC
Current, Quiescent	I _O = 0mADC		9	10		*	*		*	*	mA
TEMPERATURE RANGE											
Specification	Ambient Temperature	-25		+85	*		*	-55		+125	°C
KP, KU		0		+70							°C
	Ambient Temperature	-55		+125	*		*	*		*	°C
KP, KU	l=	-25		+85							°C
Storage	Ambient Temperature	-65		+150	*		*	*		*	°C
5											
KP, KU θ Junction-Ambient		-40	100	+125		•			↓		°C °C/W

*Specifications same as OPA404AG.

NOTE: (1) OPA404KU may be marked OPA404U.

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ELECTRICAL (FULL TEMPERATURE RANGE SPECIFICATIONS)

At V_{CC} = $\pm 15 VDC$ and T_A = T_{MIN} to T_{MAX} unless otherwise noted.

		OPA	404AG, K	P, KU		OPA404B	G		OPA404SO	3	
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	MIN	TYP	МАХ	MIN	ТҮР	МАХ	UNITS
TEMPERATURE RANGE Specification Range KP, KU	Ambient Temperature	-25 0		+85 +70	*		*	-55		+125	°C °C
INPUT OFFSET VOLTAGE Input Offset Voltage KP KU Average Drift KP, KU	V _{CM} = 0VDC		±450 ±1 ±3 ±5	2mV ±3.5		*	±1.5mV		±550 *	±2.5mV	μV mV μV/°C μV/°C
Supply Rejection		75	96		80	*		70	93		dB
BIAS CURRENT Input Bias Current	V _{CM} = 0VDC		±32	±200		*	±100		±500	±5nA	pА
OFFSET CURRENT Input Offset Current	V _{CM} = 0VDC		17	100		*	50		260	2.5nA	pА
VOLTAGE RANGE Common-Mode Input Range Common-Mode Rejection KP, KU	V _{IN} = ±10VDC	±10 82 80	±12.7, –10 99 99	.6	* 86	*		±10 + 80	+12.6, –10. 88	5	V dB dB
OPEN-LOOP GAIN, DC Open-Loop Voltage Gain	$R_L \ge 2k\Omega$	82	94		86	*		80	88		dB
RATED OUTPUT Voltage Output Current Output Short Circuit Current	$R_{L} = 2k\Omega$ $V_{O} = \pm 10VDC$ $V_{O} = 0VDC$	±11.5 ± ±5 ±8	±12.9, –13 ±9 ±20	.8 ±50	* *	* * *	*	±11 + * *	+12.7, –13. ±8 *	8	V mA mA
POWER SUPPLY Current, Quiescent	I _O = 0mADC		9.3	10.5		*	*		9.4	11	mA

* Specification same as OPA404AG.

ORDERING INFORMATION

MODEL	PACKAGE	TEMPERATURE RANGE
MODEL	TACKAGE	KANGL
OPA404KP	14-Pin Plastic DIP	0°C to +70°C
OPA404KU ⁽¹⁾	16-Pin Plastic SOIC	0°C to +70°C
OPA404AG	14-Pin Ceramic DIP	–25°C to +85°C
OPA404BG	14-Pin Ceramic DIP	–25°C to +85°C
OPA404SG	14-Pin Ceramic DIP	-55°C to +125°C

NOTE: (1) OPA404KU may be marked OPA404U.

ABSOLUTE MAXIMUM RATINGS

PACKAGE INFORMATION

MODEL	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
OPA404KP OPA404KU ⁽²⁾ OPA404AG OPA404BG	14-Pin Plastic DIP 16-Pin Plastic SOIC 14-Pin Ceramic DIP 14-Pin Ceramic DIP	010 211 169 169
OPA404SG	14-Pin Ceramic DIP	169

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix D of Burr-Brown IC Data Book. (2) OPA404KU may be marked OPA404U.

Operating Temperature Range P, U = -25°C/+85°C	C, G = −55°C/+125°C
Lead Temperature (soldering, 10s)	300°C
SOIC (soldering, 3s)	+260°C
Output Short-Circuit Duration ⁽³⁾	Continuous
Junction Temperature	+175°C

NOTES: (1) Packages must be derated based on $\theta_{JC} = 30^{\circ}$ C/W or $\theta_{JA} = 120^{\circ}$ C/W. (2) For supply voltages less than ±18VDC the absolute maximum input voltage is equal to: 18V > $V_{IN} > -V_{CC} - 8V$. See Figure 2. (3) Short circuit may be to power supply common only. Rating applies to +25°C ambient. Observe dissipation limit and T_J.

PIN CONFIGURATION





DICE INFORMATION



PAD	FUNCTION	PAD	FUNCTION
1	Output A	8	Output C
2	-Input A	9	–Input C
3	+Input A	10	+Input C
4	+V _{CC}	11	-V _{cc}
5	+Input B	12	+Input D
6	-Input B	13	–Input D
7	Output B	14	Output D

Substrate Bias: -V_{CC} NC: No connection

MECHANICAL INFORMATION

	MILS (0.001")	MILLIMETERS
Die Size	108 x 108 ±5	2.74 x 2.74 ±0.13
Die Thickness	20 ±3	0.51 ±0.08
Min. Pad Size	4 x 4	0.10 x 0.10
Backing		None

TYPICAL PERFORMANCE CURVES

 $T_A = +25^{\circ}C$, $V_{CC} = \pm 15VDC$ unless otherwise noted.









BIAS AND OFFSET CURRENT vs TEMPERATURE





TYPICAL PERFORMANCE CURVES (CONT)

 T_{A} = +25°C, V_{CC} = ±15VDC unless otherwise noted.













TYPICAL PERFORMANCE CURVES (CONT)

 T_{A} = +25°C, V_{CC} = ±15VDC unless otherwise noted.









LARGE SIGNAL TRANSIENT RESPONSE







TYPICAL PERFORMANCE CURVES (CONT)

 T_{A} = +25°C, V_{CC} = $\pm 15 VDC$ unless otherwise noted.













APPLICATIONS INFORMATION

OFFSET VOLTAGE ADJUSTMENT

The OPA404 offset voltage is laser-trimmed and will require no further trim for most applications. If desired, offset voltage can be trimmed by summing (see Figure 1). With this trim method there will be no degradation of input offset drift.



FIGURE 1. Offset Voltage Trim.

INPUT PROTECTION

Conventional monolithic FET operational amplifiers require external current-limiting resistors to protect their inputs against destructive currents that can flow when input FET gate-to-substrate isolation diodes are forward-biased. Most BIFET amplifiers can be destroyed by the loss of $-V_{CC}$.

Unlike BIFET amplifiers, the **Difet** OPA404 requires input current limiting resistors only if its input voltage is greater than 8 volts more negative than $-V_{CC}$. A 10k Ω series resistor will limit the input current to a safe value with up to ±15V input levels even if both supply voltages are lost. (See Figure 2 and Absolute Maximum Ratings).

Static damage can cause subtle changes in amplifier input characteristics without necessarily destroying the device. In precision operational amplifiers (both bipolar and FET types), this may cause a noticeable degradation of offset voltage and drift.

Static protection is recommended when handling any precision IC operational amplifier.



FIGURE 2. Input Current vs Input Voltage with ±V_{CC} Pins Grounded.

GUARDING AND SHIELDING

As in any situation where high impedances are involved, careful shielding is required to reduce "hum" pickup in input leads. If large feedback resistors are used, they should also be shielded along with the external input circuitry.

Leakage currents across printed circuit boards can easily exceed the bias current of the OPA404. To avoid leakage, utmost care must be used in planning the board layout. A "guard" pattern should completely surround the high impedance input leads and should be connected to a low-impedance point which is at the signal input potential. (See Figure 3).



FIGURE 3. Connection of Input Guard.

HANDLING AND TESTING

Measuring the unusually low bias current of the OPA404 is difficult without specialized test equipment; most commercial benchtop testers cannot accurately measure the OPA404 bias current. Low-leakage test sockets and special test fixtures are recommended if incoming inspection of bias current is to be performed.

To prevent surface leakage between pins, the DIP package should not be handled by bare fingers. Oils and salts from fingerprints or careless handling can create leakage currents that exceed the specified OPA404 bias currents.

If necessary, DIP packages and PC board assemblies can be cleaned with Freon TF[®], baked for 30 minutes at 85°C, rinsed with de-ionized water, and baked again for 30 minutes at 85°C. Surface contamination can be prevented by the application of a high-quality conformal coating to the cleaned PC board assembly.



BIAS CURRENT CHANGE vs COMMON-MODE VOLTAGE

The input bias currents of most popular BIFET operational amplifiers are affected by common-mode voltage (Figure 4). Higher input FET gate-to-drain voltage causes leakage and ionization (bias) currents to increase. Due to its cascode input stage, the extremely low bias current of the OPA404 is not compromised by common-mode voltage.



FIGURE 4. Input Bias Current vs Common-Mode Voltage.

APPLICATIONS CIRCUITS

Figures 5 through 11 are circuit diagrams of various applications for the OPA404.



FIGURE 5. Auto-Zero Amplifier.



FIGURE 6. Low-Droop Positive Peak Detector.





FIGURE 7. Voltage-Controlled Microamp Current Source.



FIGURE 8. Sensitive Photodiode Amplifier.



FIGURE 9. FET Instrumentation Amplifier with Shield Driver.





FIGURE 10. 8-Pole 10Hz Low-Pass Filter.



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FIGURE 11. Wide-Band Amplifier.





PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
OPA404AG	NRND	CDIP SB	JD	14	1	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type		OPA404AG	
OPA404BG	NRND	CDIP SB	JD	14	1	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type		OPA404BG	
OPA404KP	ACTIVE	PDIP	Ν	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA404KP	Samples
OPA404KPG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA404KP	Samples
OPA404KU	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70	OPA404KU	Samples
OPA404KU/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70	OPA404KU	Samples
OPA404KU/1KE4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70	OPA404KU	Samples
OPA404KUG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70	OPA404KU	Samples
OPA404SG	NRND	CDIP SB	JD	14	1	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type		OPA404SG	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	()	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA404KU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA404KU/1K	SOIC	DW	16	1000	367.0	367.0	38.0

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- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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